

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: John Briar : Confirmation No.: 2274  
Serial No.: 10/693,217 : Art Unit: 2811  
Filed: 10/24/2003 : Examiner: Douglas W. Owens  
For: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE  
STRUCTURE

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE**

DOES NOT AFFECT PATENT TERM ADJUSTMENT  
Under 37 CFR 1.704(c)(10)

Sir/Madam:

The following Comments are submitted in response to the Notice of Allowability dated March 14, 2006. Applicants respectfully request no reduction of the Patent Term Adjustment in accordance with Clarification of 37 CFR 1.704(c)(10) – “Reduction of Patent Term Adjustment for Certain Types of Papers Filed After a Notice of Allowance has been Mailed”, 1247 Official Gazette Patent Office 111 (June 26, 2001), which states:

“The submission of the following paper after a Notice of Allowance is not considered a failure to engage in reasonable efforts to conclude processing or examination for an application: ...(6) a response to the examiner’s reasons for allowance or a request to correct an error or omission in the ‘Notice of Allowance’ or ‘Notice of Allowability’... [underlining and deletion for clarity]

**COMMENTS**

Concerning the Examiner’s statement of reasons for allowance, it is respectfully submitted that claims 12-15, 18-20 and 23-28 are allowable because they claim a combination, which includes, *inter alia*, concepts related to those addressed by the Examiner.

Respectfully submitted,



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